



RESPONSE UNDER 37 CFR 1.116-  
EXPEDITED PROCEDURE EXAMINING  
GROUP 1765



Docket No.: 268844US0PCT

COMMISSIONER FOR PATENTS  
ALEXANDRIA, VIRGINIA 22313

ATTORNEYS AT LAW

RE: Application Serial No.: 10/529,742

Applicants: Hiroshi SHIHO, et al.

Filing Date: January 6, 2006

For: POLISHING PAD FOR SEMICONDUCTOR WAFER  
AND LAMINATED BODY FOR POLISHING OF  
SEMICONDUCTOR WAFER EQUIPPED WITH THE  
SAME AS WELL AS METHOD FOR POLISHING OF  
SEMICONDUCTOR WAFER

Group Art Unit: 1765

Examiner: CHEN, KIN CHAN

SIR:

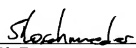
Attached hereto for filing are the following papers:

**Request for Reconsideration**

Our credit card payment form in the amount of \$0.00 is attached covering any required fees. In the event any variance exists between the amount enclosed and the Patent Office charges for filing the above-noted documents, including any fees required under 37 C.F.R. 1.136 for any necessary Extension of Time to make the filing of the attached documents timely, please charge or credit the difference to our Deposit Account No. 15-0030. Further, if these papers are not considered timely filed, then a petition is hereby made under 37 C.F.R. 1.136 for the necessary extension of time. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

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